

HZM27FA

Silicon Epitaxial Planar Zener Diode for Surge Absorb

REJ03G1213-0400 (Previous: ADE-208-443C) Rev.4.00 Jun 14, 2005

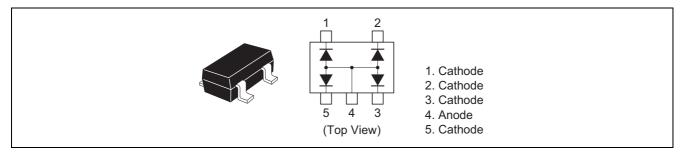
Features

- HZM27FA has four devices, and can absorb surge.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HM27FA	<u>2</u> 7A	MPAK-5	PLSP0005ZC-A (MPAK-5)

Pin Arrangement





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Тј	150	°C
Storage temperature	Tstg	–55 to +150	°C

Note: Four device total, See Fig.2.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	25.10	—	28.90	V	$I_Z = 2 \text{ mA}, 40 \text{ ms pulse}$
Reverse current	I _R	-	—	2	μA	V _R = 21 V
Capacitance	С	-	(27) * ²	—	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r _d	-	—	70	Ω	I _Z = 2 mA
ESD-Capability * ³	—	30	—	—	kV	C = 150 pF, R = 330 Ω , Both forward and reverse direction 10 pulse.

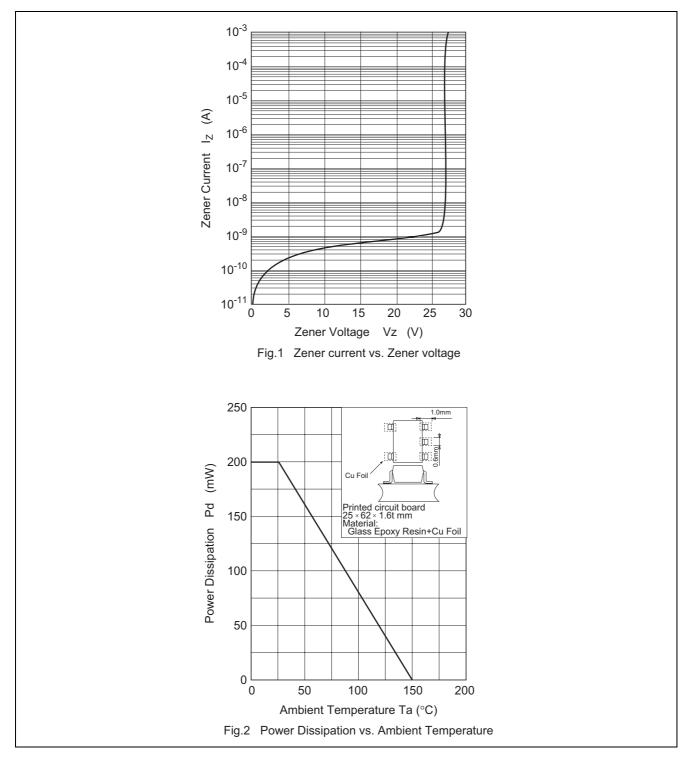
Notes: 1. Per one device

2. Reference only

3. Failure criterion ; I_R > 2 μA at V_R = 21 V

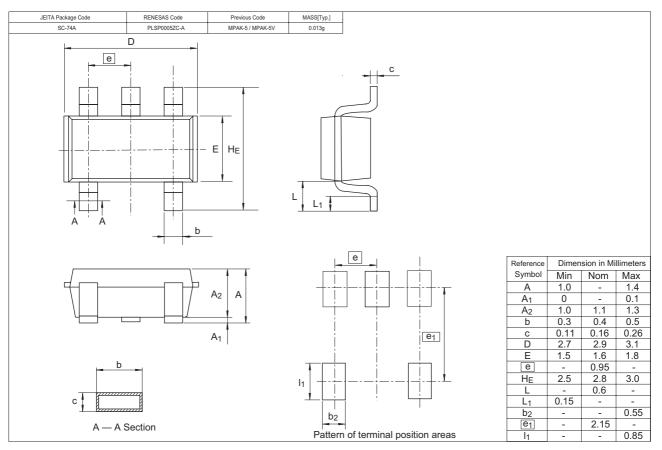


Main Characteristic





Package Dimensions





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